

Electronic Patent Application Fee Transmittal

Application Number:	10597066
Filing Date:	10-Jul-2006
Title of Invention: METHOD OF FORMING THIN SGOI WAFERS WITH HIGH RELAXATION AND LOW STACKING FAULT DEFECT DENSITY	
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Filer:	Yuanmin Cai/Maureen DiDonato
Attorney Docket Number:	FIS920030342US1

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
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Basic Filing:

Pages:

Claims:

Miscellaneous-Filing:

Petition:

Application for patent term adjustment	1455	1	200	200
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Patent-Appeals-and-Interference:

Post-Allowance-and-Post-Issuance:

Extension-of-Time:

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Miscellaneous:				
Total in USD (\$)				200